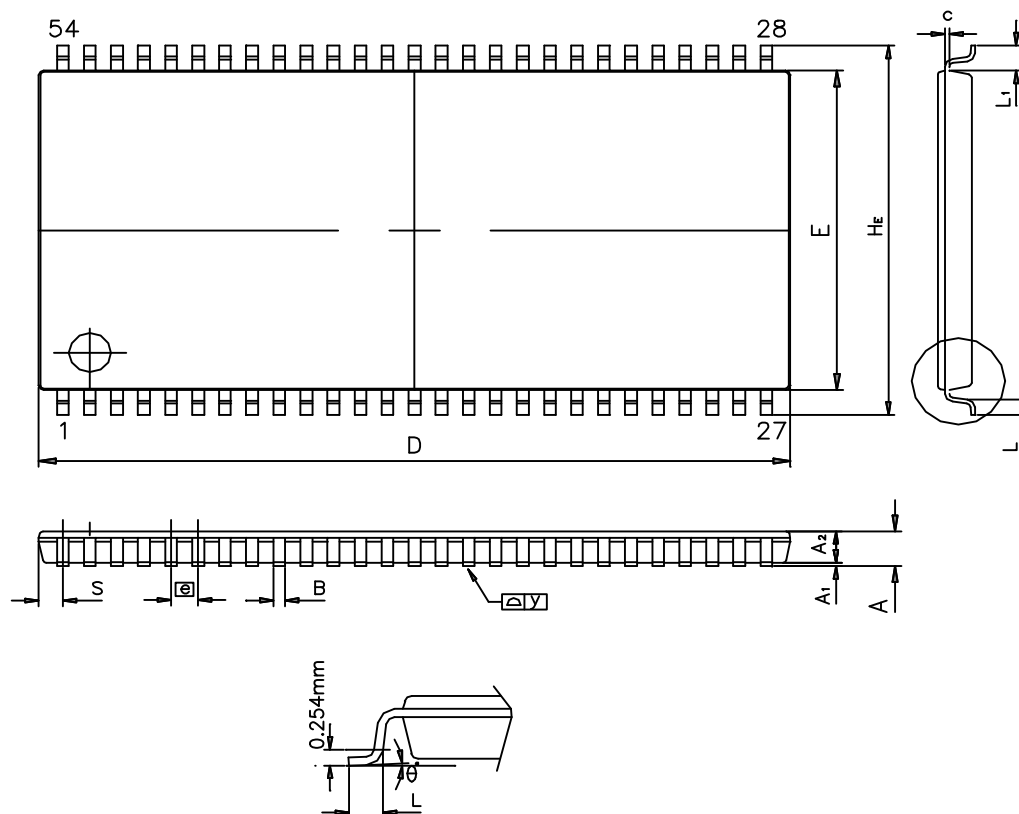


Package Dimension

(400 mil; 54 pin; Thin Small Outline Package)



SYMBOL	MILLIMETER			INCH		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A			1.20			0.047
A1	0.05	0.10	0.15	0.002	0.004	0.006
A2	0.95	1.00	1.05	0.037	0.039	0.041
B	0.30	0.35	0.45	0.012	0.014	0.018
c	0.12		0.21	0.005		0.008
D	22.22 BSC			0.875 BSC		
H _E	11.56	11.76	11.96	0.460	0.463	0.470
E	10.03	10.16	10.29	0.390	0.400	0.410
e	0.80 BSC			0.031		
L	0.40	0.50	0.60	0.016	0.020	0.024
L1	0.80 REF			0.031 REF		
S	0.71 REF			0.028 REF		
θ	0 °	-	8 °	0 °	-	8 °

Note:

1. Dimension D does not include mold protrusions or gate burrs.
2. Mold protrusion and gate burrs shall exceed 0.15 mm per side.
3. Dimension E1 does not include interlead mold protrusions.
4. Interlead mold protrusions shall not exceed 0.25 mm per side.